
2SD467

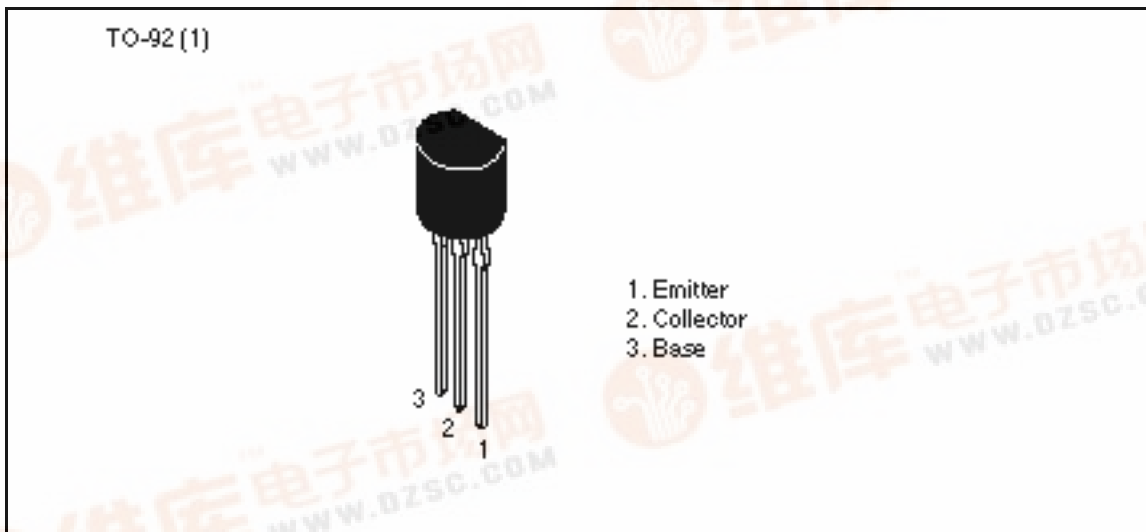
Silicon NPN Epitaxial

HITACHI

Application

- Low frequency power amplifier
- Complementary pair with 2SB561

Outline



2SD467

Absolute Maximum Ratings (Ta = 25°C)

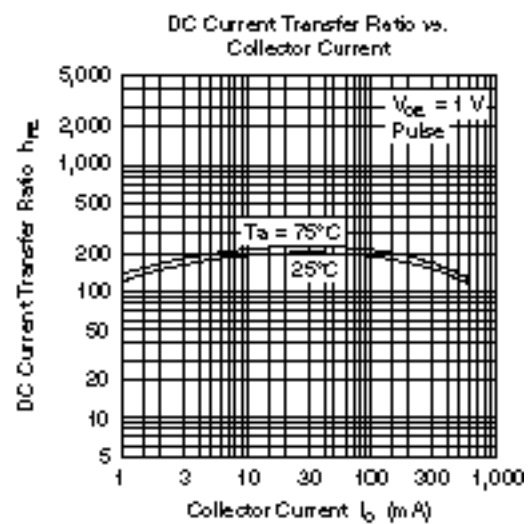
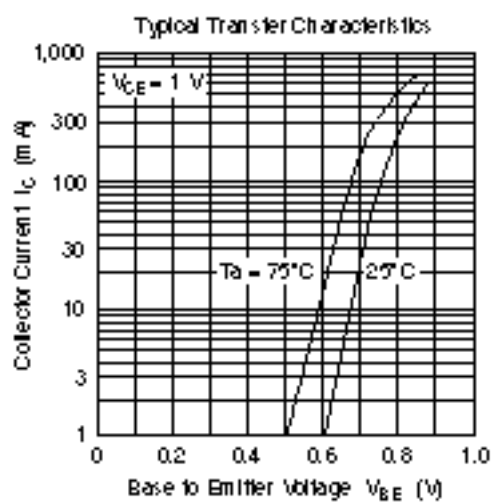
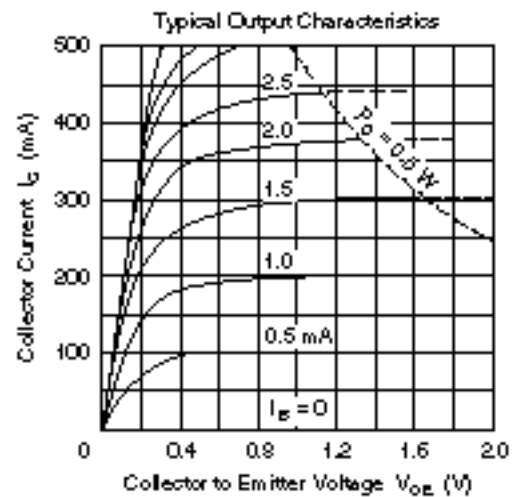
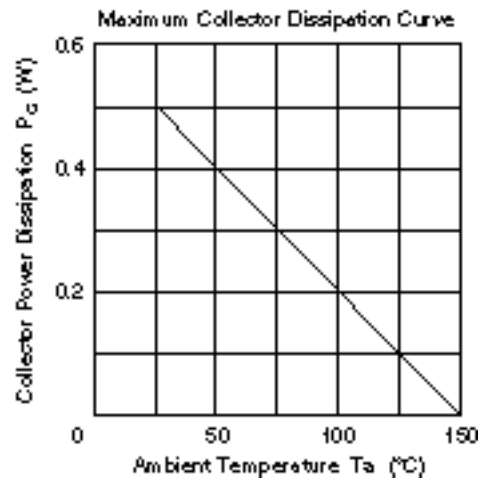
Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	25	V
Collector to emitter voltage	V_{CEO}	20	V
Emitter to base voltage	V_{EBO}	5	V
Collector current	I_C	0.7	A
Collector peak current	$i_{C(peak)}$	1.0	A
Collector power dissipation	P_C	0.5	W
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	–55 to +150	°C

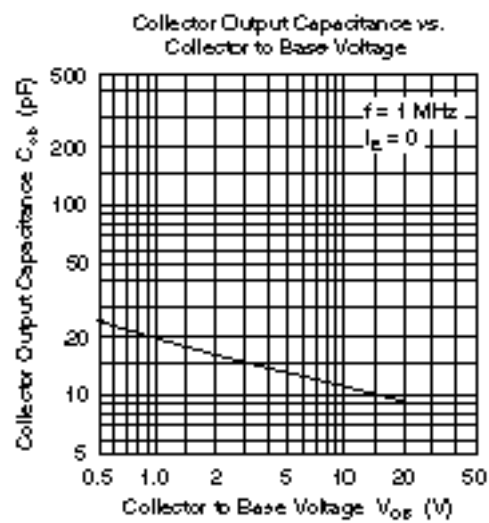
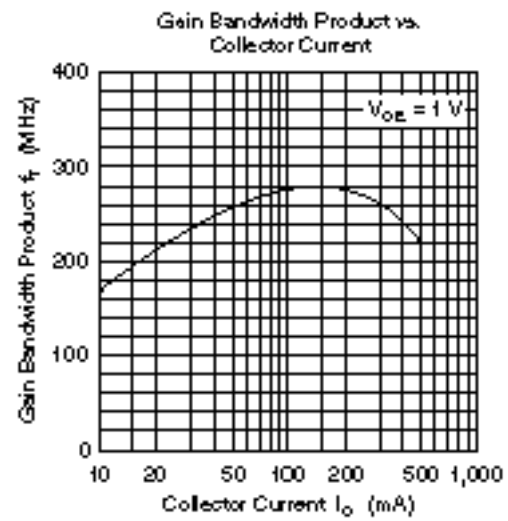
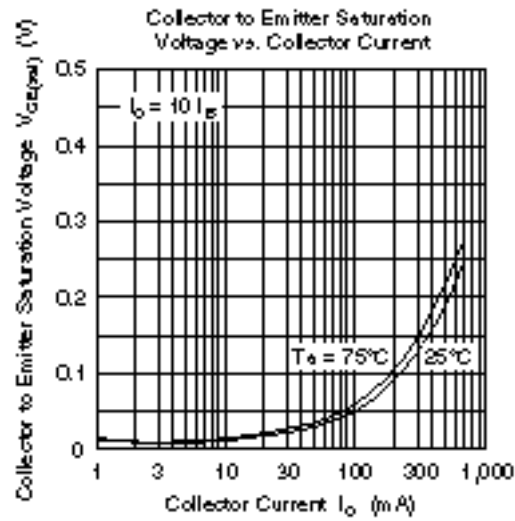
Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	25	—	—	V	$I_C = 10 \mu A, I_E = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	20	—	—	V	$I_C = 1 \text{ mA}, R_{BE} =$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	5	—	—	V	$I_E = 10 \mu A, I_C = 0$
Collector cutoff current	I_{CBO}	—	—	1.0	μA	$V_{CB} = 20 \text{ V}, I_E = 0$
DC current transfer ratio	h_{FE}^{*1}	85	—	240		$V_{CE} = 1 \text{ V}, I_C = 0.15 \text{ A}$ (Pulse test)
Collector to emitter saturation voltage	$V_{CE(sat)}$	—	0.19	0.5	V	$I_C = 0.5 \text{ A}, I_B = 0.05 \text{ A}$ (Pulse test)
Base to emitter voltage	V_{BE}	—	0.76	1.0	V	$V_{CE} = 1 \text{ V}, I_C = 0.15 \text{ A}$ (Pulse test)
Gain bandwidth product	f_T	—	280	—	MHz	$V_{CE} = 1 \text{ V}, I_C = 0.15 \text{ A}$ (Pulse test)
Collector output capacitance	C_{ob}	—	12	—	pF	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$

Note: 1. The 2SD467 is grouped by h_{FE} as follows.

B	C
85 to 170	120 to 240





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